

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6528409".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:26
L2	673242	nickel ni	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:27
L3	1	1 and 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:27
L4	368126	hf hafnium pd palladium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:40
L5	671418	nickel ni!	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:33
L6	202309	solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:33
L7	3011104	throughhole or through adj hole or via adj hole or viahole or via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:40
L8	135497	ti/tin wn or tan or hfn or (titanium tantalum tungsten hafnium) near2 nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:40
L9	6	L4 same L8 same L7 same L5 same L6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:33
L10	283162	activating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:34

L11	31937	electroless near4 plat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:35
L12	8314	11 near4 5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:35
L13	0	7 same 8 same 10 near8 4 and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:36
L14	8	7 same (8 or tin) and 10 near8 4 and 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:40
L15	237381	pd palladium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:40
L16	370554	ti/tin wn or tan or hfn or (titanium tantalum tungsten halfnium) near2 nitride tin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:40
L17	3014114	throughhole or through adj hole or via adj hole or viahole or via or through adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:48
L18	4	17 same 16 same 15 same 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:48
L19	47	17 same 16 and 15 same 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:43
L20	11	17 same 16 and 15 same 12 same 17	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:48

L21	7	20 not 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:43
L22	3077574	throughhole or through adj hole or via adj hole or viahole or via or through adj wafer damascene trench	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:48
L23	4	22 same 16 same 15 same 12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:48
L24	11	22 same 16 and 15 same 12 same 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:48
L25	370	17 same 16 same 5 same 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 16:06
L26	9	17 same 16 same 12 same 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 16:05
L27	21	17 same 8 same 5 same 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 16:06
L28	4013	((438/637) or (438/672) or (438/667) or (438/675) or (438/678)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/21 16:44
S95	3	((("6107109") or ("6114240") or ("6294837"))).PN.	USPAT	OR	OFF	2004/11/26 15:55
S96	276	throggh adj wafer or through-wafer or throughwafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:48

S97	277334	tin or titanium adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:49
S98	4404	ald or atomic adj layer adj deposit\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:03
S99	1	S96 and S97 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:48
S10 0	367445	tin wn or tan or hfn or (titanium tantalum tungsten halfnium) near2 nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:20
S10 1	1	S96 and S100 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:05
S10 2	1	S96 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:23
S10 3	522040	throughhole or through adj hole or via adj hole or viahole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:06
S10 4	162	S103 and S97 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:26
S10 5	13	S103 same S97 same S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:12
S10 7	31688	electroless near4 plat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:50

S10 8	365442	hf hafnium pd palladium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:19
S10 9	16	S103 and S97 and S98 and S107 and S108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:27
S11 0	658267	nickel ni	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:27
S11 1	16	S103 and S97 and S98 and S107 and S108 and S109	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 16:27
S11 2	5	S103 and S97 and S98 and S107 and S108 and S110	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:12
S11 3	2	"6528409".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:12
S11 4	4829417	temperature or degree or celcius or centigrade	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:12
S11 5	1	S113 and S114	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:12
S11 6	1	S113 and S114 and S98	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:13
S11 7	1	S113 and S114 and S98 and (cvd or chemical adj vapor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:25

S11 8	651	tdmat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:25
S11 9	24	S98 same S97 same S118	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:26
S12 0	7	S98 same S97 same S118 same S114	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/26 17:27
S12 1	286	throg h adj wafer or through-wafer or throughwafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:48
S12 2	286	throg h adj wafer or through-wafer or throughwafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:48
S12 3	279463	tin or titanium adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:48
S12 4	4551	ald or atomic adj layer adj deposit\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:48
S12 5	1	S122 and S123 and S124	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:49
S12 6	365536	tin tan wn hfn or (titanium tungsten tantalum hafnium)adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:55
S12 7	31926	electroless near4 plat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:35

S12 8	673063	nickel ni	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:52
S12 9	1	S122 and S126 and S127 same S128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:52
S13 0	3734837	plat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:54
S13 1	230569	plating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:58
S13 2	59	S121 and S126 and S130	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:55
S13 3	128310	tan wn hfn or (titanium tungsten tantalum hafnium)adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:48
S13 4	19	S121 and S133 and S130	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:57
S13 5	9	S121 and S133 and S131	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 18:58
S13 6	255341	plating electroplating electro-plating electro adj plating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 19:00
S13 7	19	S121 and S133 and S136	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 19:01

S13 8	255341	plating electroplating electro-plating electro adj plating (electroless electro adj less electro-less) near2 plating	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 19:01
S13 9	19	S121 and S133 and S138	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:24
S14 0	2	"6528409".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:24
S14 1	1	S140 and (ni or nickel)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:24
S14 2	525521	throughhole or through adj hole or via adj hole or viahole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:20
S14 3	31926	electroless near4 plat\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:27
S14 4	367973	hf hafnium pd palladium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:27
S14 5	16	S142 and S123 and S124 and S143 and S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:27
S14 6	1171221	activat\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:30
S14 7	289	S142 same S146 same S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:48



S14 8	13011	S143 same S128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:28
S14 9	112	S147 and S148	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:29
S15 0	8314	S143 near4 S128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:28
S15 1	82	S147 and S150	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:29
S15 2	874119	activating activated	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:34
S15 3	146	S142 same S152 same S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:32
S15 4	55	S153 and S150	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:32
S15 5	16	S142 same S152 near8 (layer barrier coating) same S144	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:32
S15 6	7	S155 and S150	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:33
S15 7	128310	tan wn hfn or (titanium tungsten tantalum hafnium)adj nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:48

S15 8	5	S142 same S146 same S144 same S157	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:49
S15 9	3	S158 and S128	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/20 20:49
S16 0	368126	hf hafnium pd palladium	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:19
S16 1	370554	tin wn or tan or hfn or (titanium tantalum tungsten hafnium) near2 nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:28
S16 2	525689	throughhole or through adj hole or via adj hole or viahole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:29
S16 3	671418	nickel ni!	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:21
S16 4	202309	solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:21
S16 5	1493	S160 and S161 and S162 and S163 and S164	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:22
S16 6	35	S160 same S161 same S162 same S163 same S164	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:30
S16 7	33	S166 and (@ad < "20040220")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:23

S16 8	370554	"TiN" wn or tan or hfn or (titanium tantalum tungsten hafnium) near2 nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:29
S16 9	3011104	throughhole or through adj hole or via adj hole or viahole or via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:38
S17 0	135497	ti/tin wn or tan or hfn or (titanium tantalum tungsten hafnium) near2 nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:29
S17 1	6	S160 same S170 same S169 same S163 same S164	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:33
S17 2	80	S160 same (S170 tin) same S169 same S163 and (S169 near8 S164)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:37
S17 3	199757	(throughhole or through adj hole or via adj hole or viahole or via).ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:41
S17 5	14	S172 and S173	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:41
S17 6	1376282	(throughhole or through adj hole or via adj hole or viahole or via).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:41
S17 7	36	S172 and S176	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 12:41
S17 8	27	S177 not S175	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/21 15:26